





X1000 series

FLEXIBLE LASER DIRECT IMAGING SOLUTION FOR PCB INNER- AND OUTER LAYER AND SOLDER MASK APPLICATIONS



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The X1000 series is an universal and cost-efficient Laser Direct Imaging (LDI) system platform designed for the use in high-mix/ low-volume PCB manufacturing environments. The system is flexible deployable to the dry-film patterning or solder mask imaging process.

The new X1000 LDI system platform ensures maximum efficiency and throughput - i.e. from the use of LIMATA's proprietary **LUVIR Technology** (UV/IR) imaging technology for solder mask imaging - at lowest possible Costs of Ownership over the equipment life-cycle.

Ideal for PCB manufacturers (or special PCB divisions of larger PCB makers) with high-mix/low-volume production mixes or imaging output requirements of up to 750 panels per day in a multi-shift operational mode (HDI, standard-rigid, flex). An optimized system operations footprint further provides for an easier placement and system movement within each facility.

Complementary customized X1000 automation features for the fully-automated direct imaging of i.e. reel-to-reel flex PCB's are available upon request.



NEW: X1000 A modular in-line automation

Features and Benefits

- Flexible LDI platform for dry-film patterning and solder mask applications available in three imaging capacity configurations (X1100 / X1200 / X1300)
- UV-laser diode wavelength set-up combined with IR laser
 LUVIR Technology ensures fastest solder mask process speed and throughput capacities of up to 750 panels per day*
- Highly-accurate panel registration (multi-point sub-registration approach)
- Longer lifetime of imaging unit and lower TCO's through use of UV-laser diodes and galvo-scanning mirror technology
- Ease of use operator friendly handling and data interface
- Small and compact operational machine footprint ensures fast placement and deployment to all PCB manufacturing environments
- Fully modular and flexible automation system X1000A available in single and twin configuration

* based on conventional ink types and 3-shift operational mode

Applications

· Standard / HDI / FLEX PCB production

Solder Mask imaging examples







X1000 System specifications

Market:	High-mix / flexible PCB production	
Operating table:	Single drawer system	
Vacuum table:	Included	
Mechanical system:	XY Linear motor	
Base:	Full granite	
Weight:	ca. 1,500 kg	
Dimensions:	2,4 m x 1,2 m x 1,8 m / 94" x 47" x 71"	
Footprint:	2 m ²	
Communication interface:	Ethernet	
Power supply:	220-230 VAC 50/60Hz / 1 Phase	
Upgradeable:	Up to 3 heads (X1300)	
Max. image size:	660 x 610 mm ² / 26" x 24"	
Extended working area (option):	812 x 610 mm ² / 32" x 24"	
Max. panel thickness:	20μm - 15 mm / 0.8 mil - 0.6"	

Imaging Features

UV Light engine:	Diode lasers
UV Laser wavelength:	400-410 nm
IR Light engine:	IR fiber laser
UV & IR Lifetime laser [typ.:]	> 25.000 h
UV Lasers per head:	4 - 6
Number of heads (exposure units):	1-3
Depth of focus:	+/- 500µm / 20mil

Resolution Accuracy**	Solder Mask
Min. dams:	50 μm / 2 mil
Min. S.R.O:	50 μm / 2 mil
Max. edge roughness:	+/- 10% min. res.
Max line width tolerance:	+/- 10% min. res.

Resolution Accuracy**	Dry-Film
Min. Lines (HD-Option):	25 μm / 1 mil
Min. Space (HD-Option):	25 μm / 1 mil
Max. edge roughness:	+/- 10% min. res.
Max line width tolerance:	+/- 10% min. res.

Registration Features

Up to 3 x HD Cameras
RGB / IR
< +/- 25 μm / 1.0 mil
< +/- 10 μm / 0.4 mil



X1000 with reel - to reel automation for Flex-PCB

For more information please contact us!

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^{*} depending on fiducial and layout quality

^{**} depending on resist material

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Solder Mask Option (LUVIR Technology)

- Unique UV/IR Laser setup for optimized and faster solder mask imaging (on all conventional ink types)
- All common colors can be processed with optimized speed & accuracy

Standard system features

HD-Option

- Adjustable laser spot size for advanced HDI production
- Processing of lines / spaces down to 1 mil /25 um

Multi-Point Registration

 Detection of multiple fiducials for max. registration quality

Traceability & MES - Interfaces

 Individual QR-Codes / Barcodes or serial numbers can be imaged on the fly

Automation options

- NEW: X1000A Limata inhouse developed inline automation single and twin
- · R2R automation
- · Endless XXL option

MES data interface programming options

- Customized interface programming (ERP / production data bases)
- Industrie 4.0 realtime production overview and predictive maintanance capability











LUVIR Technology







X1000 modular system capacity configurations

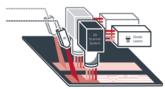


LDI System family	X1100	X1200	X1300
UV laser heads	1	2	3
UV diode lasers / spots per head	4/6	4/6	4/6
Total UV lasers / spots	4/6	8/12	12/18
IR Laser Modules (Solder mask)	1	2	3

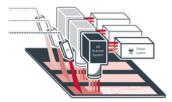
Modularity



X1100



X1200



X1300